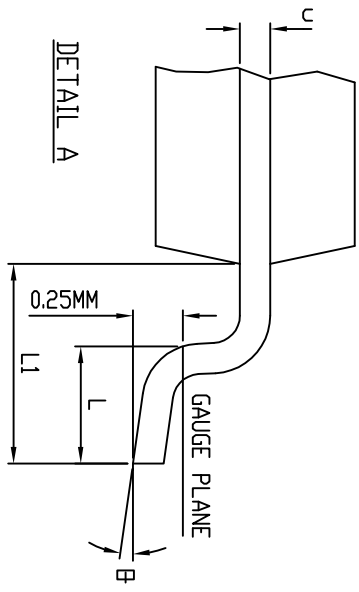
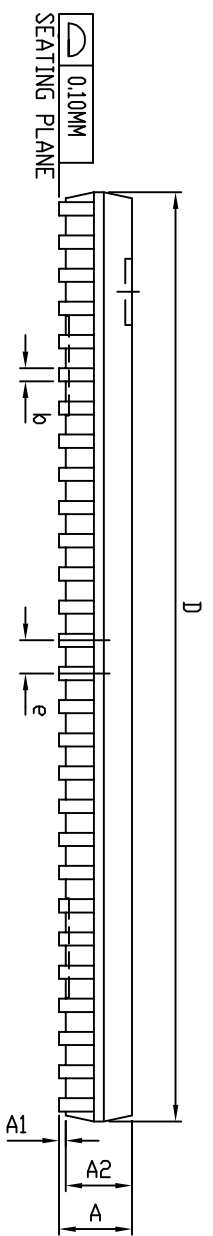


DETAIL A

- NOTES**
1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
  2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
  3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
  4. LEAD COPPLANARITY IS 0.003 INCH MAX.



SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN.	NDM	MIN.	NDM
A		1.20		.047
A1	0.05	0.15	.002	.006
A2	0.80	1.00	.031	.039
D	13.90	14.00	.547	.551
E	8.00	8.10	.315	.319
E1	6.00	6.10	.236	.240
L	0.45	0.60	.018	.024
L1	1.00 REF.		.039 REF.	
b	0.18	0.20	.007	.008
e	0.50 BSC.		.020 BSC.	
c	0.09		.004	
Ø	0		0	
N			56	
REF	JEDEC MO-153 VARIATION EE			



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TITLE:  
 POD for 56LTD TSSOP (240 MIL),  
 0.50MM PITCH

DATE: 08/06/08  
 DOCUMENT NO. SL/POD-00026  
 REV. A  
 Page 1 of 2



## Document History Page

Document Title: POD for 56LD TSSOP (240 MIL), 0.50MM PITCH

Document Number: SL/POD-00026 Rev. A

Rev.	ECR No.	Date	Orig. of Change	Description of Change
A	ECR-722	8/6/2008	RP	NEW RELEASE